

Customer Information Notification

Issue Date:17-Apr-2020Effective Date:18-Apr-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

MPC5775E/MPC5775B Data

Sheet Updates To Rev.2

2020030331

QUALITY

	Change Category					
	[] Wafer Fab Process	[] Assembly	[] Product Marking	[] Test	[] Design	
		Process		Location		
	[] Wafer Fab Materials	[] Assembly	[] Mechanical Specification	ו[]Test	[] Errata	
		Materials		Process		
] Wafer Fab Location	[] Assembly	[]	[]Test	[] Electrical	
		Location	Packing/Shipping/Labeling	Equipment	spec./Test	
			5 11 5 5		coverage	
I	[] Firmware	[X] Other - Datasheet update for clarification				

Description

NXP Semiconductors announces data sheet update for the MPC5775E/MPC5775B from revision 1 to revision 2. The revision history included in the updated document provides a details description of the changes.

Data sheet changes:

1. Page 79: In Figure 42, added optional feature field S.

2. Page 23: In Table 16, updated the footnote (no.13) from "TUE does not apply to differential conversions" to "TUE, Gain, and Offset specifications do not apply to differential conversions".

3. Page 11: In Table 4, added Max value 120uA for 40°C and 360uA for 85°C for ISTBY.

4. Page 30: In Table 17, changed the condition of dGROUP from "Within pass band: Tclk is fADCD_M / 2" to "Within pass band: Tclk is 2/fADCD_M".

5. Page 31: Updated the footnote (no.15) of tLATENCY, changed the Register Latency formula from "where fADCD_S is the after-decimation ADC output data rate, fADCD_M is the modulator sampling rate and fFM_PER_CLK is the frequency of the peripheral bridge clock feeds to the ADC S/D module. REGISTER LATENCY = tLATENCY + 0.5/fADCD_S + 2 (\sim +1)/fADCD_M + 2(\sim +1)/fFM_PER_CLK" to "where fADCD_S is the after-decimation ADC output data rate, fADCD_M/2 is the modulator sampling rate and fFM_PER_CLK" to "where fADCD_S + 2 (\sim +1)/fADCD_M + 2(\sim +1)/fFM_PER_CLK" to "where fADCD_S is the after-decimation ADC output data rate, fADCD_M/2 is the modulator sampling rate and fFM_PER_CLK is the frequency of the peripheral bridge clock feeds to the ADC S/D module. REGISTER LATENCY = tLATENCY = tLATENCY + 0.5/fADCD_S + 2 (\sim +1)/fADCD_M + 2(\sim +1)/fFM_PER_CLK".

The MPC5775E/MPC5775B data sheet revision 2 is attached to this notice and can be found at: https://www.nxp.com/products/processors-and-microcontrollers/power-architecture/mpc55xx-5xxx-mcus/ultra-reliablempc57xx-mcus/mpc5775b-and-mpc5775e-microcontrollers-for-battery-management-systems-bms-and-inverterapplications:MPC5775B-E?tab=Documentation Tab

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02. Reason

The data sheet has been updated to provide additional technical clarification.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team. About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	Support			
NXP Privacy Policy Terms of Use					
NXP Semiconductors High Tech Campus, 5656 AG Eindhoven, The Netherlands					

© 2006-2010 NXP Semiconductors. All rights reserved.

Affected Part Numbers SPC5775BDK3MME2 SPC5775EDK3MME3